

PRODUCT SPECIFICATION

Customer : _____

Part No : XY-3528-1-01-HWC

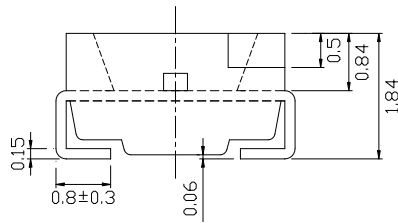
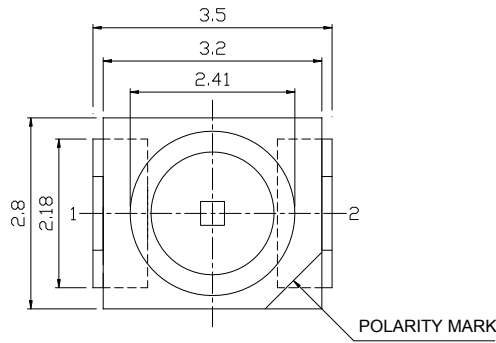
Developed No : _____

Date : _____

CUSTOMER APPROVED BY

APPROVED	Q.C.	R&D

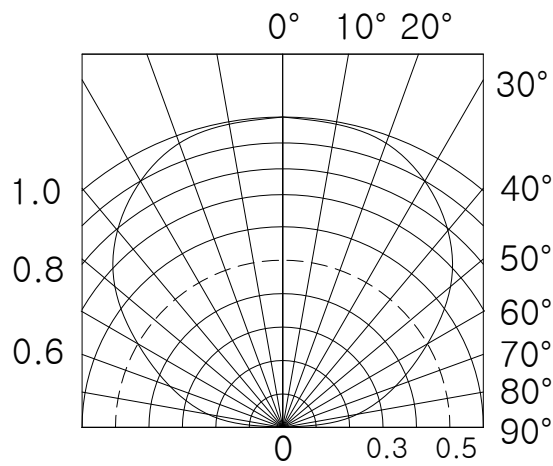
■ **Outline Dimension:**



Notes:

1. All dimensions are in millimeters.
2. Tolerance is ± 0.2 unless otherwise noted.
3. Specifications are subject to change without notice.

■ **View Angle:**



SPATIAL DISTRIBUTION

■ **Typical Electrical & Optical Characteristics(Ta=25°)**

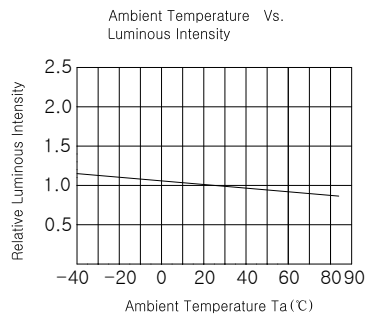
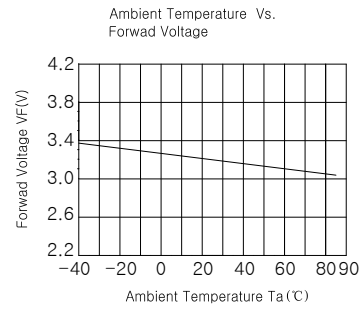
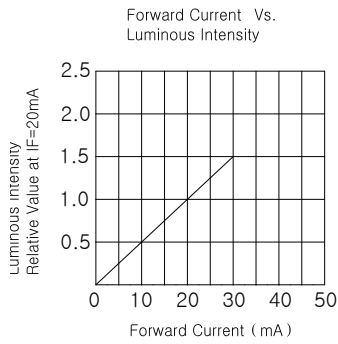
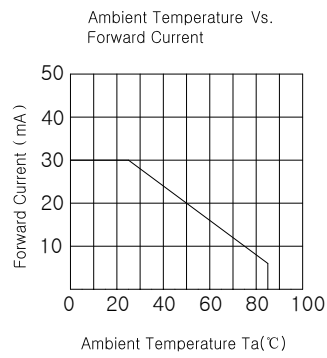
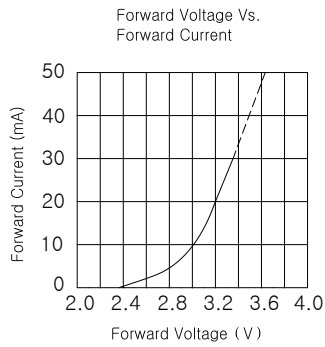
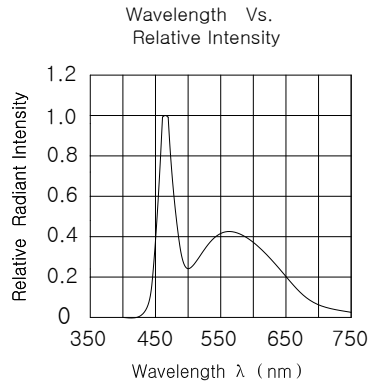
Items	Symbol	Condition	Min	Typ	Max	Unit
Forward Voltage	VF	IF=20mA	3.0	3.2	3.4	V
Reverse Current	IR	VR=5V	---	---	5	μ A
Chromaticity Coordinates	X	IF=20mA	6500	7000	--	
	Y	IF=20mA	6500	7000	--	
Luminous Intensity	Iv	IF=20mA	1800	2000	2300	mcd
View Angle	2 θ 1/2	IF=20mA	---	120	---	Deg

■ **Absolute Maximum Ratings (Ta = 25°C)**

Items	Symbol	Absolute maximum Rating	Unit
Power Dissipation	PD	120	mW
Forward Current(DC)	IF	30	mA
Peak Forward Current	IFP	120	mA
Reverse Voltage	VR	5	V
Operation Temperature	Topr	- 40~ + 85	°C
Storage Temperature	Tstg	- 40~ + 85	°C

Note :1/10 Duty Cycle, 0.1 ms Pulse Width.

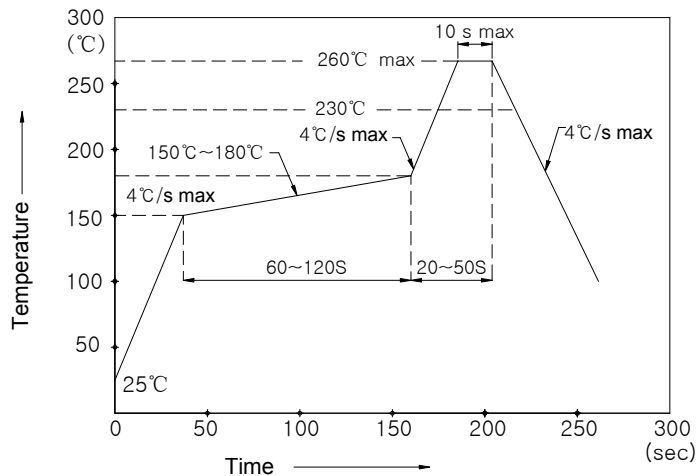
■ Typical Electrical/Optical Characteristics Curves:



■ Reliability Test :

Classification	Test Item	Test Conditions	Duration	Units Tested	Number of Damaged
Life Test	Operating Life Test	Ta=25°C ± 5°C, RH=55 ± 20%RH, IF=30mA	1000hrs	22	0/22
Environment Test	High Temperature Storage	Ta =100°C ± 10°C	1000hrs	22	0/22
	Low Temperature Storage	Ta = - 40°C ⁺³ ₋₅ °C	1000hrs	22	0/22
	Temp & Humidity Storage	Ta =85°C ⁺⁵ ₋₃ °C RH=85 ⁺⁵ ₋₁₀ %RH	1000hrs	22	0/22
	Thermal Shock Test	Ta= - 40°C ⁺⁵ ₋₃ °C ~ 100°C ⁺³ ₋₅ °C T=5min - 5min	100 Cycles	22	0/22
	Temperature Cycling Test	Ta= - 40 ⁺³ ₋₅ °C ~ 25°C ~ 100 ⁺⁵ ₋₃ °C ~ 25°C T=30min-5min-30min- 5min	10Cycles	22	0/22

Reflow Soldering Profile For Lead-free SMT Process.



NOTES:

1. We recommend the reflow temperature 245°C (+/-5°C). The maximum soldering temperature should be limited to 260°C.
2. Don't cause stress to the epoxy resin while it is exposed to high temperature.
3. Number of reflow process shall be 2 times or less.

